

N-Channel Enhancement Mode Field Effect Transistor

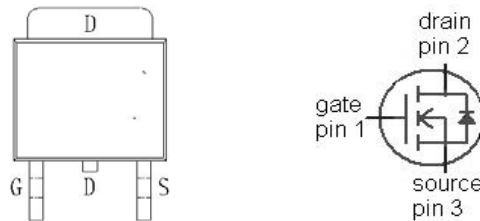
● Features

- N-channel, normal level
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC for target application
- Ideal for high-frequency switching and synchronous rectification

● Product Summary

| | | |
|--------------------------|-----|----|
| V_{DS} | 100 | V |
| $R_{DS(on),max}$ (TO252) | 78 | mΩ |
| $(I_{DM})^b$ | 52 | A |

● Pin Configurations(TO252)



Top View

● Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

| Parameter | | Symbol | Maximum | Units | |
|--|-------------------------|-----------------|------------|-------|-------|
| Drain-Source Voltage | | V_{DS} | 100 | V | |
| Gate-Source Voltage | | V_{GS} | ±20 | | |
| Continuous Drain Current($T_J=150^\circ\text{C}$) ^a | $T_A=25^\circ\text{C}$ | I_D | 13 | A | |
| | $T_A=100^\circ\text{C}$ | | 9 | | |
| Pulsed Drain Current ^b | | I_{DM} | 52 | | |
| Avalanche Current ^b | L=0.1mH | I_{AS} | 65 | | |
| Avalanche energy | | E_{AS} | 17 | mJ | |
| Power Dissipation ^a | $T_A=25^\circ\text{C}$ | P_D | 31 | W | |
| | $T_A=70^\circ\text{C}$ | | 15 | | |
| Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to 150 | °C | |
| Thermal Characteristics | | | | | |
| Parameter | | Symbol | Typ | Max | Units |
| Maximum Junction-to-Ambient ^a | $t \leq 5\text{s}$ | $R_{\theta JA}$ | 78 | 100 | °C/W |
| | Steady-State | | 120 | 150 | |
| Maximum Junction-to-Lead | | $R_{\theta JL}$ | 40 | 50 | |

Notes

a. Surface Mounted on 1x1FR4 Board.

b. Pulse width limited maximum junction temperature Pulse test: $PW \leq 300 \mu\text{s}$ duty cycle $\leq 2\%$

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● Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|----------------------------|--|--|------------------------|-----|-----------|------------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=1\text{mA}, V_{GS}=0\text{V}$ | 100 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=100\text{V}, V_{GS}=0$ | $T_A=25^\circ\text{C}$ | | 1 | μA |
| | | | $T_A=70^\circ\text{C}$ | | 60 | |
| I_{GSS} | Gate-Body leakage current | $V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$ | | | ± 0.1 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$ | 2 | | 4 | V |
| $I_{D(ON)}$ | On state drain current ^a | $V_{GS}=10\text{V}, V_{DS}\geq 15\text{V}$ | 13 | | | A |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ^a | $V_{GS}=10\text{V}, I_D=13\text{A}$ | | | 78 | $\text{m}\Omega$ |
| | | $V_{GS}=8\text{V}, I_D=13\text{A}$ | | | 100 | |
| g_{FS} | Forward Trans conductance ^a | $V_{DS}=15\text{V}, I_D=10\text{A}$ | 7 | 13 | | S |
| V_{SD} | Diode Forward Voltage | $I_S=13\text{A}, V_{GS}=0\text{V}$ | 0.3 | | 1.2 | V |
| I_S | Maximum Body-Diode Continuous Current | | | | 3 | A |
| Dynamic^b | | | | | | |
| C_{iss} | Input capacitance | $V_{GS}=0\text{V}, V_{DS}=50\text{V}, f=1\text{MHz}$ | | 538 | 716 | pF |
| C_{oss} | Output capacitance | | | 76 | 101 | |
| C_{rss} | Reverse transfer capacitance | | | 8 | 12 | |
| Q_g | Total Gate Charge | $V_{GS}=10\text{V}, V_{DS}=50\text{V},$ $I_D=13\text{A}, R_G=2.4\ \Omega$ | | 8 | 11 | nC |
| Q_{gs} | Gate - Source Charge | | | 3 | 4 | |
| Q_{gd} | Gate - Drain Charge | | | 2 | 3 | |
| R_g | Gate resistance | | 0.5 | | 2.5 | |
| Switching | | | | | | |
| $t_{D(on)}$ | Turn-On Delay Time | $V_{GS}=10\text{V}, V_{DS}=50\text{V}, R_L=30\Omega,$ $R_{GEN}=2.4\Omega, I_D=13\text{A}$ | | 9 | 13 | ns |
| t_r | Turn-On Rise Time | | | 4 | 6 | |
| $t_{D(off)}$ | Turn-Off Delay Time | | | 13 | 18 | |
| t_f | Turn-Off Fall Time | | | 3 | 4 | |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=3\text{A}, dI/dt=100\text{A}/\mu\text{s}$ | | 67 | 90 | |

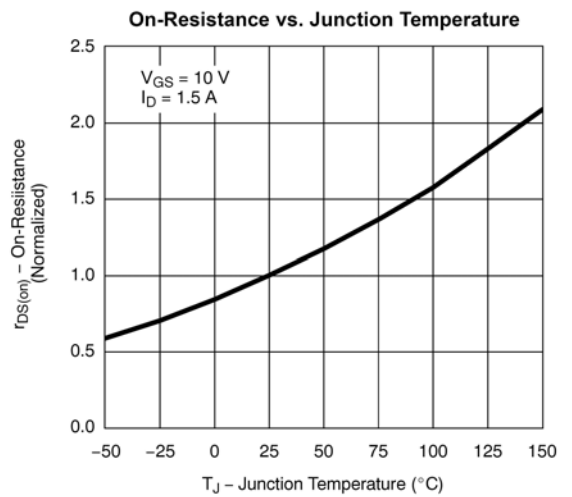
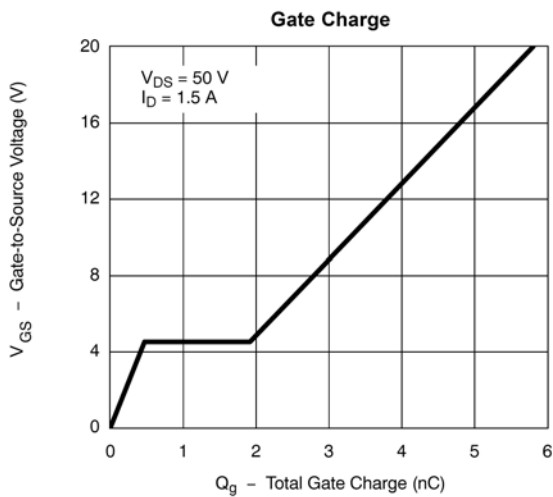
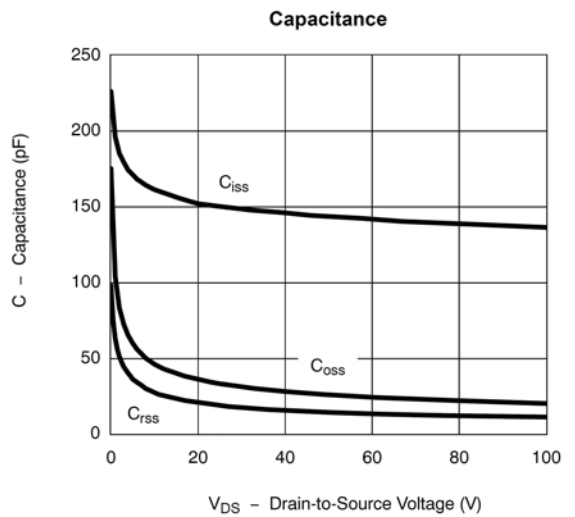
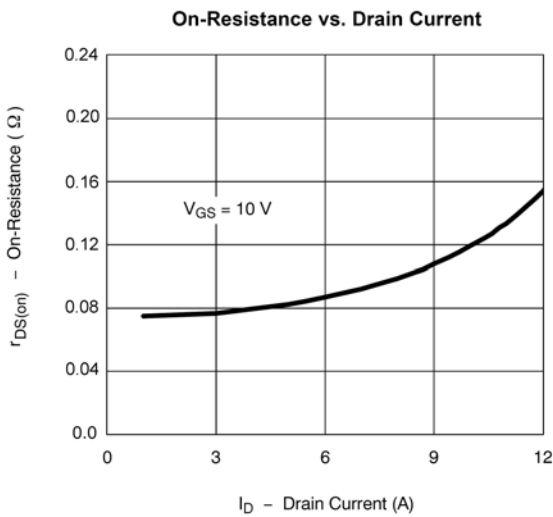
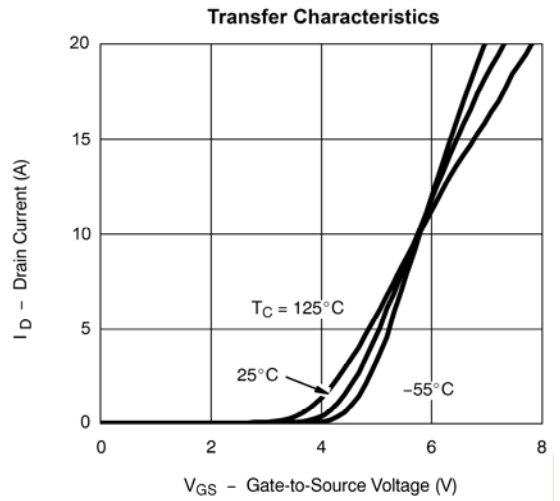
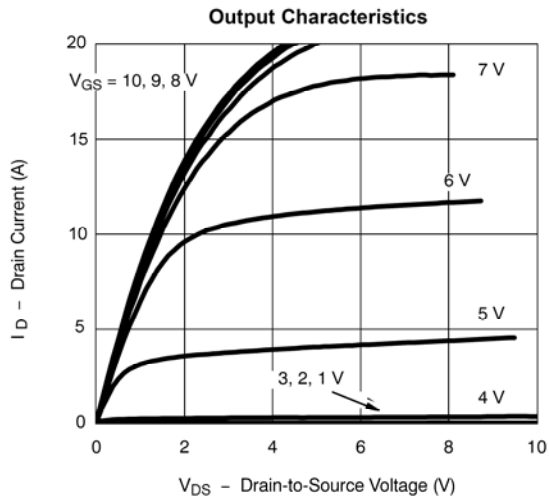
Notes

a. Pulse test: $PW\leq 300\ \mu\text{s}$ duty cycle $\leq 2\%$

b. Guaranteed by design, not subject to production testing.

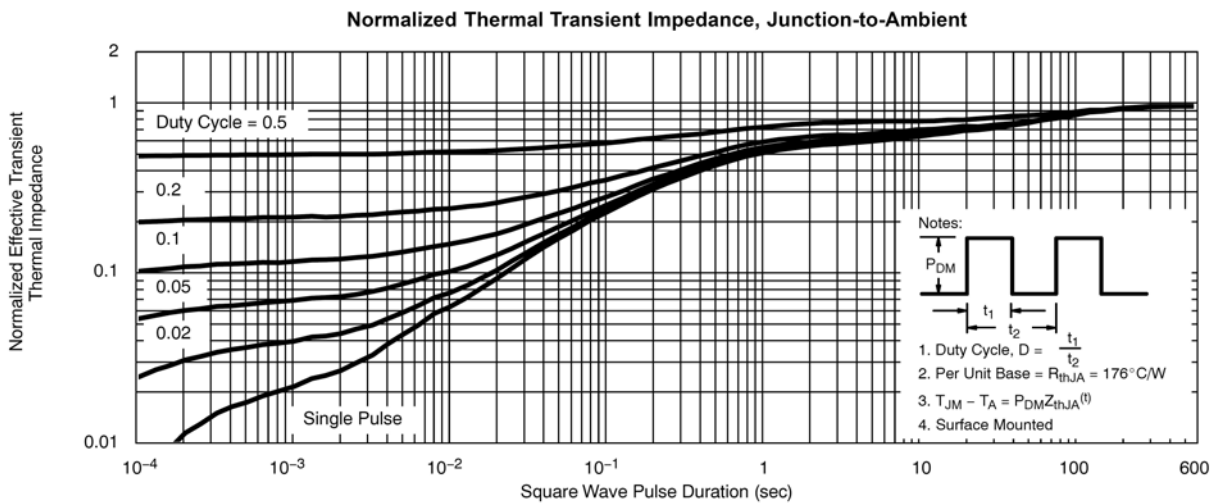
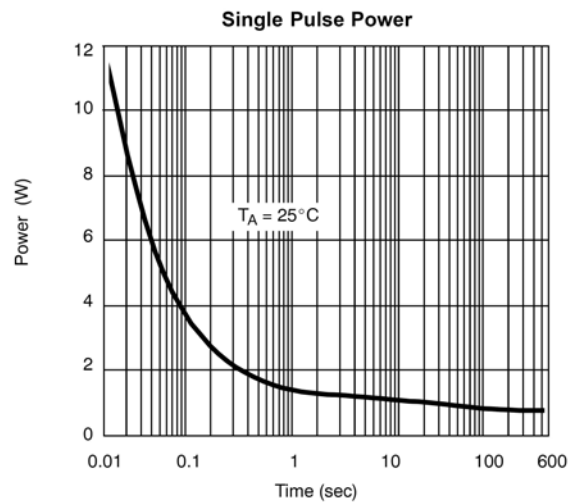
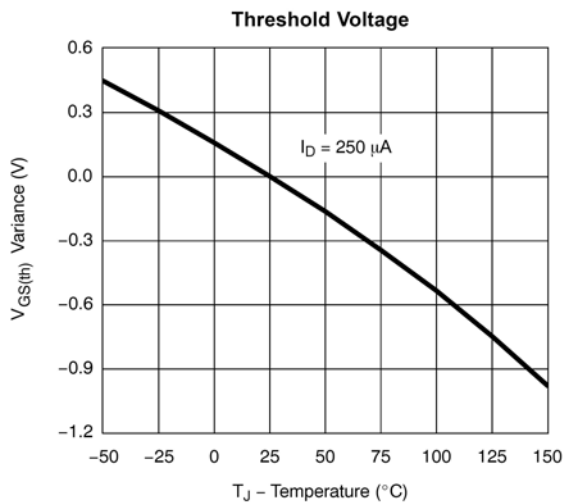
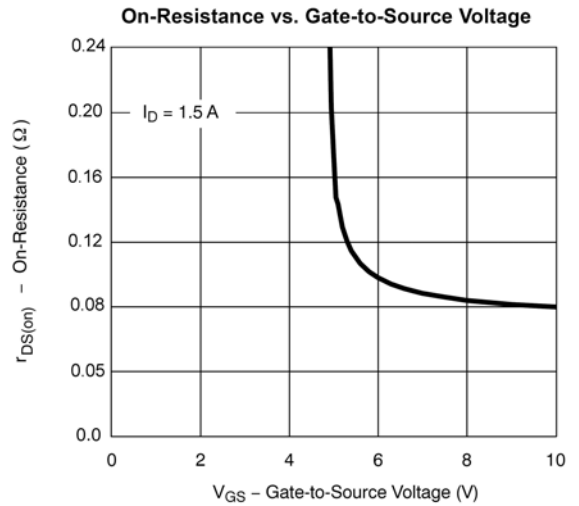
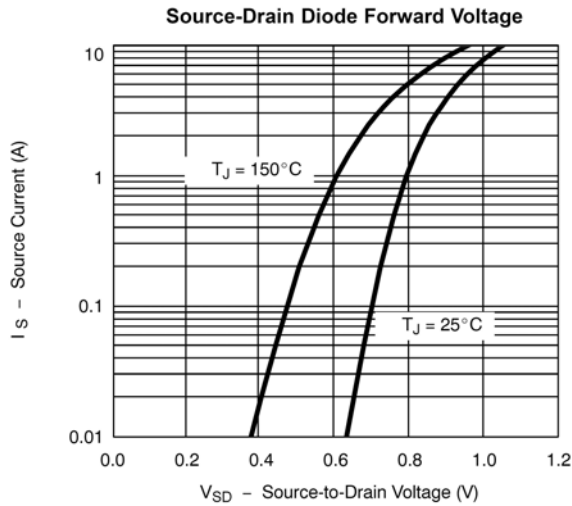
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● TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



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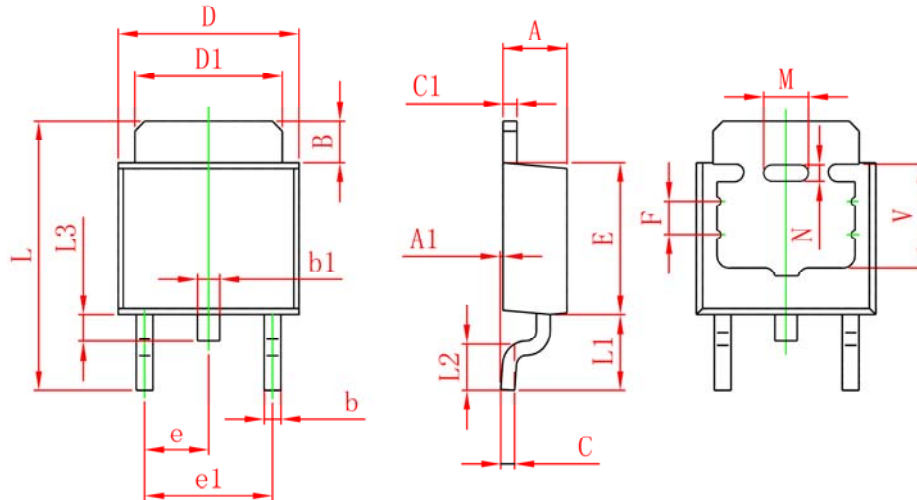
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- Package Information

TO-252C-2L PACKAGE OUTLINE DIMENSIONS



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| B | 1.350 | 1.650 | 0.053 | 0.065 |
| b | 0.500 | 0.700 | 0.020 | 0.028 |
| b1 | 0.700 | 0.900 | 0.028 | 0.035 |
| c | 0.430 | 0.580 | 0.017 | 0.023 |
| c1 | 0.430 | 0.580 | 0.017 | 0.023 |
| D | 6.350 | 6.650 | 0.250 | 0.262 |
| D1 | 5.200 | 5.400 | 0.205 | 0.213 |
| E | 5.400 | 5.700 | 0.213 | 0.224 |
| e | 2.300 TYP. | | 0.091 TYP. | |
| e1 | 4.500 | 4.700 | 0.177 | 0.185 |
| F | 1.200REF. | | 0.047REF. | |
| M | 1.600REF. | | 0.063REF. | |
| N | 0.450REF. | | 0.018REF. | |
| L | 9.500 | 9.900 | 0.374 | 0.390 |
| L1 | 2.550 | 2.900 | 0.100 | 0.114 |
| L2 | 1.400 | 1.780 | 0.055 | 0.070 |
| L3 | 0.600 | 0.900 | 0.024 | 0.035 |
| V | 3.800 REF | | 0.150 REF | |